

SOT570-2

plastic thin fine-pitch ball grid array package; 180 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA180
Package type industry code	TFBGA180
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.8	-	12	12.2	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	[tbd]	-	[tbd]	1.2	mm
A ₂	package height	0.75	-	0.8	0.85	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	180	-	



2. Package outline

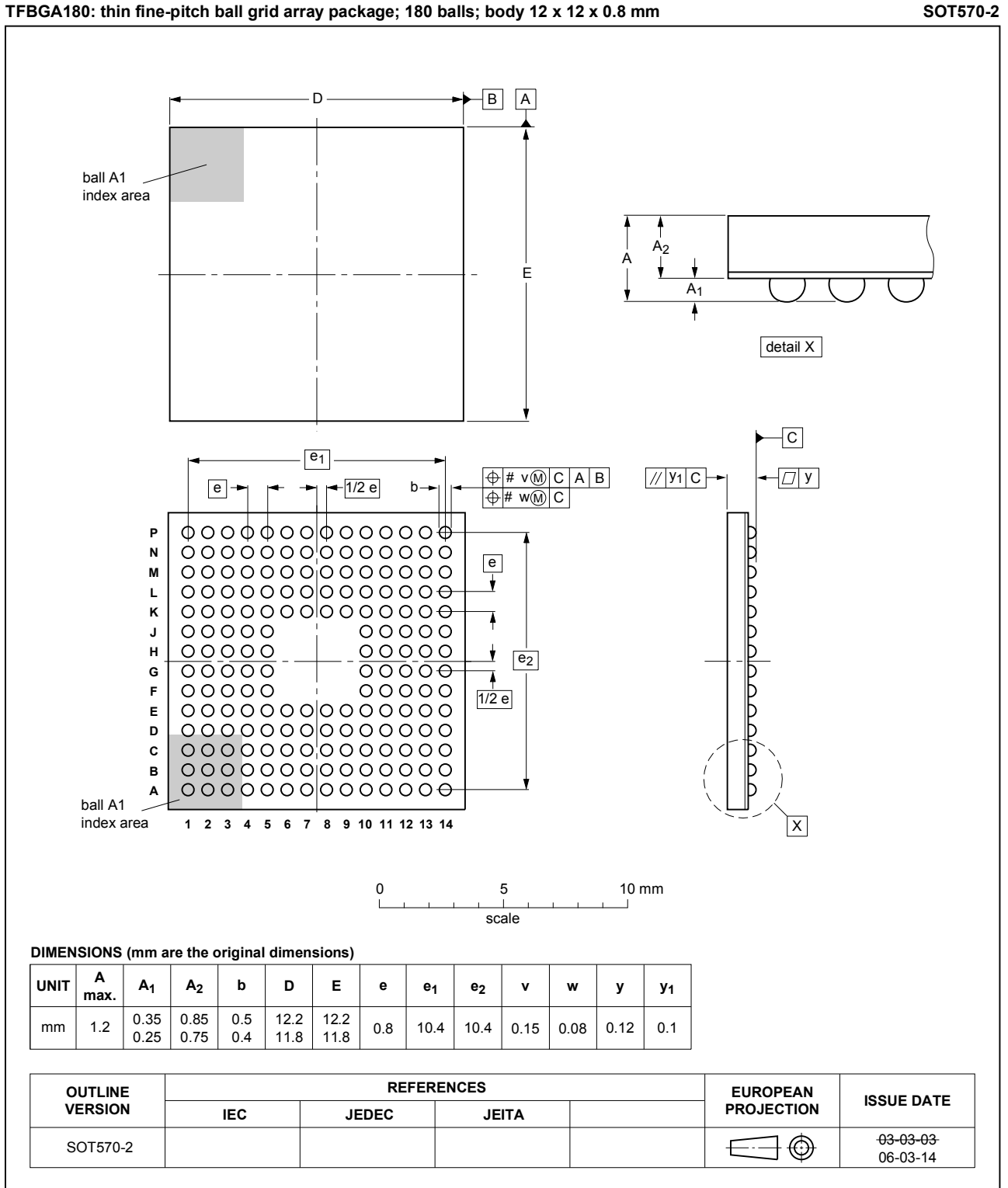


Fig. 1. Package outline TFBGA180 (SOT570-2)

3. Soldering

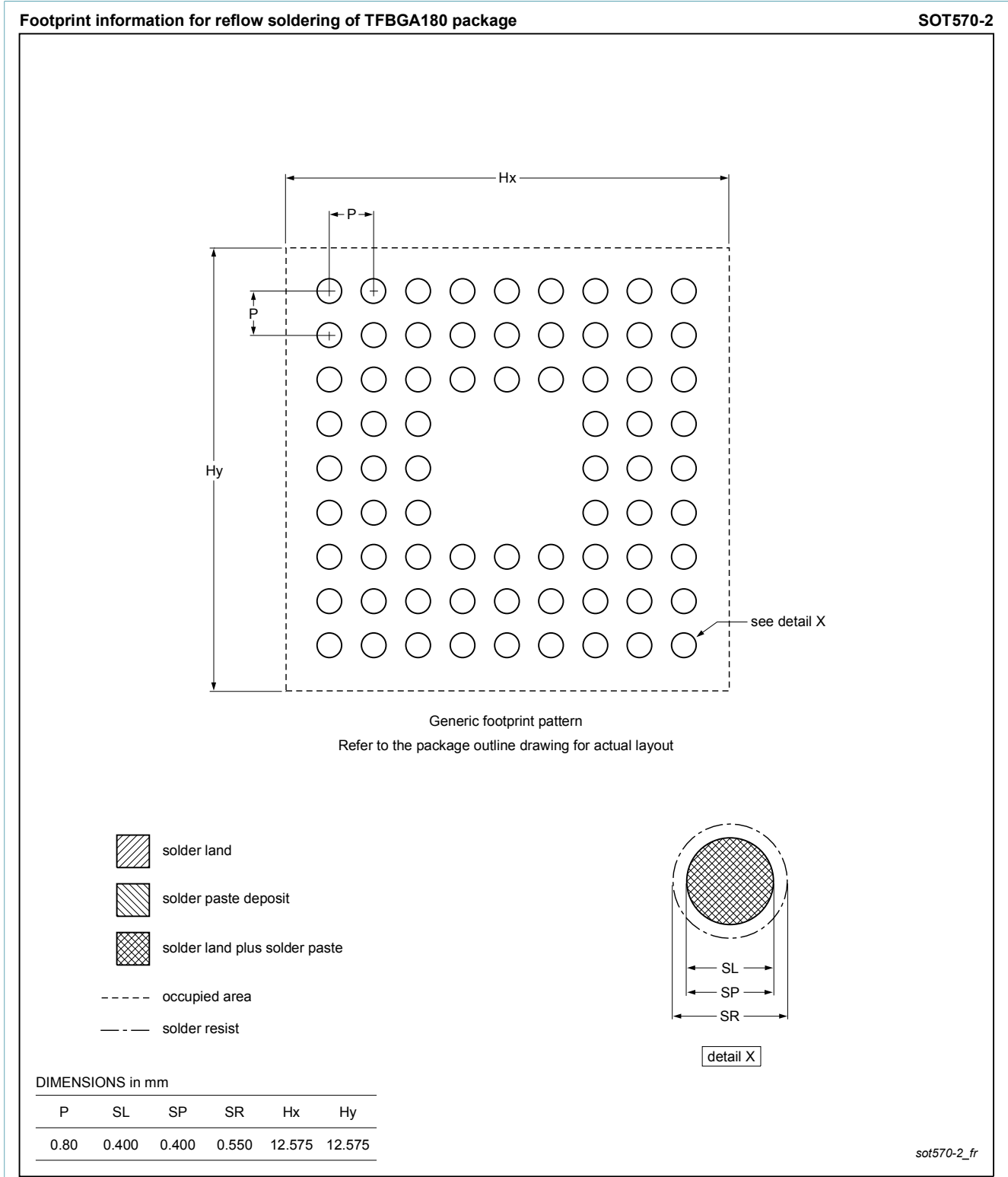


Fig. 2. Reflow soldering footprint for TFBGA180 (SOT570-2)

4. Legal information

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